AU9254 A21 USB Hub Controller Technical Reference Manual

Revision 1.1



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1.0 Introduction

1.1. Description

The AU9254A21 is an integrated single chip USB hub controller designed for the emerging industry-standard Universal Serial Bus (USB). The AU9254A21 supports four USB downstream ports. Each downstream port has power switch control, and over-current sensing.

Single chip integration makes the AU9254A21 the most cost effective stand-alone USB hub solution available in the market. Downstream ports can be used to connect various USB peripheral devices, such as USB printers, modems, scanners, cameras, mice, or joysticks to the system without adding external glue logic.

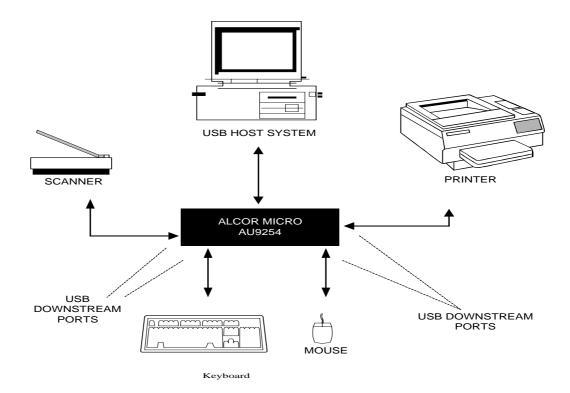
1.2. Features

- Fully compliant with the Universal Serial Bus Specification, version 1.1.
- USB hub design is compliant with Universal Serial Bus Hub Specification, revision 1.1.
- Single chip integrated USB hub controller with embedded proprietary processor.
- Supports four bus-powered/self-powered downstream ports.
- Built-in 3.3v voltage regulator allows single +5V operating voltage, resulting in reduced overall system cost.
- Runs at 12Mhz frequency.
- 28-pin SSOP package, both normal size (body size 209 mil) and smaller size (body size 150 mil) are available.

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2.0 Application Block Diagram

The AU9254A21 is a single chip 4-port USB hub controller. The upstream port is connected to the USB system. The downstream ports can be used for a mouse, joystick, scanner, printer or other device.



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3.0 Pin Assignment

The AU9254A21 is packaged as a 28-pin shrink small outline plastic package (SSOP). The figure on the following page shows the signal names for each of the pins on the chip. Accompanying the figure is the table that describes each of the pin signals.

	1		1	
USB2_DM	1	0	28	USB1_DP
USB2_DP	2		27	USB1_DM
USB3_DM	3		26	USB_DP
USB3_DP	4		25	USB_DM
USB4_DM	5		24	DP3_OVRCUR
USB4_DP	6	ALCOR MICRO	23	DP4_OVRCUR
DP4_PWRUP	7	AU9254 A21 USB HUB	22	DP3_PWRUP
DP2_PWRUP	8	CONTROLLER	21	XTAL2
BUS_PWRED	9	28 - PIN SSOP	20	XTAL1
VCC50/VCC5IK	10		19	AGND/GNDO
GND50/GND5IK	11		18	NC
VCC3V	12		17	DP2_OVRCUR
DP1_PWRUP	13		16	SUSPEND
GANGPOWER	14		15	DP1_OVRCUR

Table 3-1. Pin Descriptions of Au9254A21, 28-pin SSOP

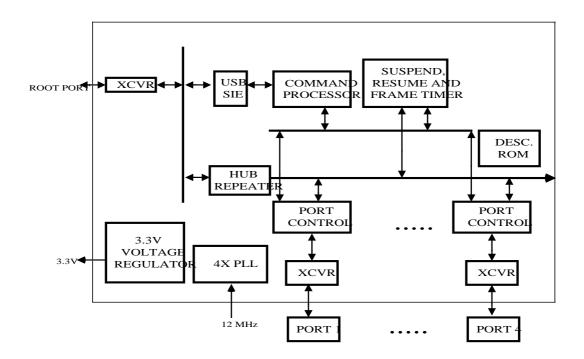
	Table 3-1. Pin Descriptions of Auy254A21, 28-pin 55OP						
Pin No	Pin Name	Input/Output	Description				
1	USB_DM	Input/Output	USB D- for downstream port 2; add $15 \mathrm{K}\Omega$ pull-down to ground.				
2	USB2_DP	Input/Output	USB D+ for downstream port 2; add $15K\Omega$ pulldown to ground.				
3	USB3_DM	Input/Output	USB D- for downstream port 3; add $15K\Omega$ pull-down to ground.				
4	USB3_DP	Input/Output	USB D+ for downstream port 3; add $15K\Omega$ pulldown to ground.				
5	USB4_DM	Input/Output	USB D- for downstream port 4; add 15K Ω pull-down to ground.				
6	USB4_DP	Input/Output	USB D+ for downstream port 4; add $15K\Omega$ pulldown to ground.				
7	DP4_PWRUP	Output	Downstream port 4 power switch control. Active low.				
8	DP2_PWRUP	Output	Downstream port 2 power switch control. Active low.				
9	BUS_PWRED	Input	Bus power. Low indicates bus-powered.				
10	VCC5O/VCC5IK	Power	+5 V power supply.				
11	GND5O/GND5IK	Power	Ground.				
12	VCC3V	Power	3.3V output for upstream D+ pull-up.				
13	DP1_PWRUP	Output	Downstream port 1 power switch control. Active low.				
14	GANGPOWER	Input	Ganged or individual port power selection. Add a 10k pull down for ganged power. 10k pull up for individual power.				
15	DP1_OVRCUR	Input	Downstream port 1 over-current indicator. Active low.				

16	SUSPEND	Output	Device is in suspended state: Active high.
17	DP2_OVRCUR	Input	Downstream port 2 over-current indicator. Active low.
18	NC		
19	AGND/GNDO	Power	+5 V power supply.
20	XTAL_1	Input	Crystal in.
21	XTAL_2	Output	Crystal out.
22	DP3_PWRUP	Output	Downstream port 3 power switch control. Active low.
23	DP4_OVRCUR	Input	Downstream port 4 over-current indicator. Active low.
24	DP3_OVRCUR	Input	Downstream port 3 over-current indicator. Active low.
25	USB_DM	Input/Output	USB D- for upstream.
26	USB_DP	Input/Output	USB D+ for upstream port. Need external 1.5K Ω pull-up to 3.3V.
27	USB1_DM	Input/Output	USB D- for downstream port 1; add 15K Ω pull-down to ground.
28	USB1_DP	Input/Output	USB D+ for downstream port 1; add 15K Ω pulldown to ground.

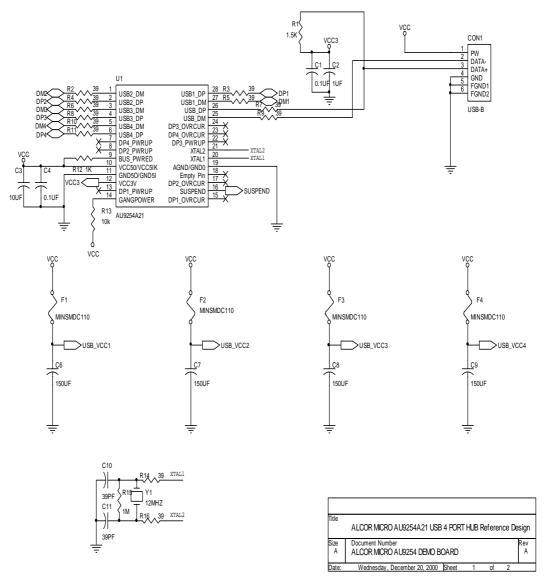
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4.0 System Architecture and Reference Design

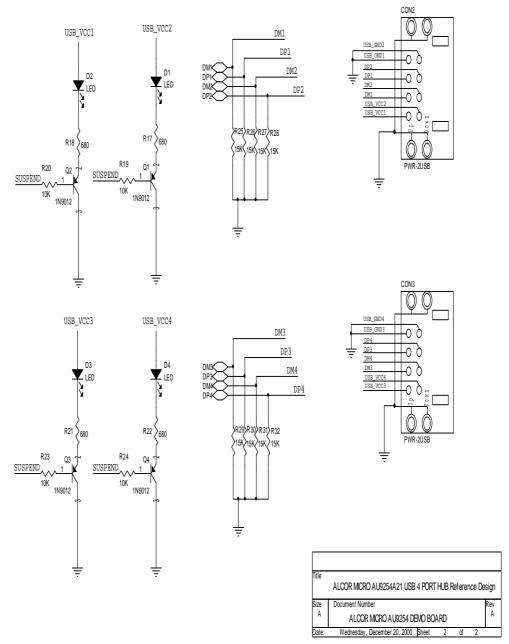
4.1. AU9254A21 Block Diagram



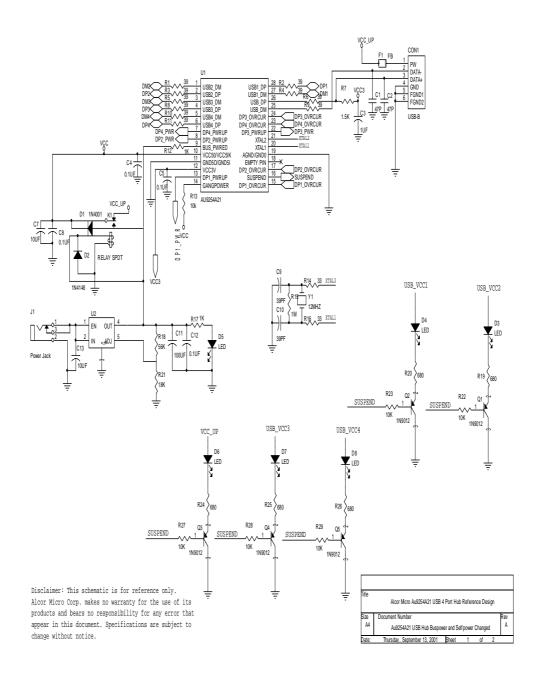
4.2 Sample Schematics

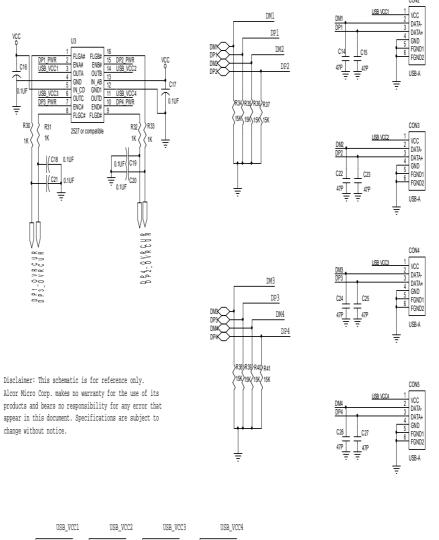


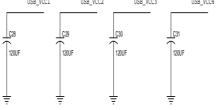
Disclaimer: This schematic is for reference only. Alcor Micro Corp. bears no responsibility for any error that appear in this document. Specifications are subject to change without notice.

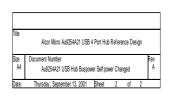


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5.0 Electrical Characteristics

5.1. Absolute Maximum Ratings

SYMBOL	PARAMETER	RATING	UNITS
V_{CC}	Power Supply	-0.3 to 6.0	V
$V_{\rm IN}$	Input Voltage	-0.3 to VCC+0.3	V
V_{OUT}	Output Voltage	-0.3 to VCC+0.3	V
T_{STG}	Storage Temperature	-40 to 125	С

5.2. Recommended Operating Conditions

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
V_{CC}	Power Supply	4.5	5.0	5.5	V
V_{IN}	Input Voltage	0		V_{CC}	V
T_{OPR}	Operating Temperature	-5		85	o _C

5.3. General DC Characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$ m I_{IL}$	Input low current	no pull-up or pull-down	-1		1	μΑ
I_{IH}	Input high current	no pull-up or pull-down	-1		1	μΑ
I_{OZ}	Tri-state leakage current		-10		10	μΑ
C_{IN}	Input capacitance			4		ρF
C_{OUT}	Output capacitance			4		ρF
C_{BID}	Bi-directional buffer capacitance			4		ρF

5.4. DC Electrical Characteristics for 5 volts operation

(Under Recommended Operating Conditions and $V_{CC}=4.5v \sim 5.5v$, Tj= -40°C to + 85°C)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{ m IL}$	Input Low Voltage	TTL			0.8	V
$V_{ m IL}$	Input Low Voltage	CMOS			$0.3*V_{CC}$	V
$V_{ m IL}$	Schmitt input Low Voltage	TTL		1.10		V
$V_{ m IL}$	Schmitt input Low V oltage	CMOS		1.84		V
$V_{ m IH}$	Input High Voltage	TTL	2.2			V
$V_{ m IH}$	Input Hight Voltage	CMOS	$0.7*V_{CC}$			V
$V_{ m IH}$	Schmitt input High Voltage	TTL		1.87		V
$V_{ m IH}$	Schmitt input High Voltage	CMOS		3.22		V
V_{OL}	Output low voltage	I _{OL} =2, 4, 8, 12, 16, 24 mA			0.4	V
V_{OH}	Output high voltage	I _{OH} =2, 4, 8, 12, 16, 24 mA	3.5			V
R_{I}	Input Pull-up/down resistance	Vil=0 _V or Vih=V _{CC}		50		ΚΩ

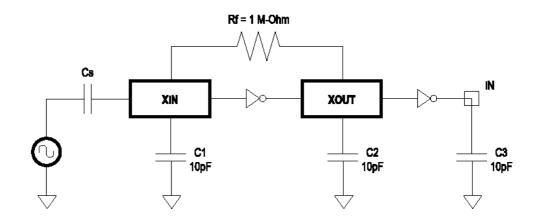
5.5. DC Electrical Characteristics for 3.3 volts operation

(Under Recommended Operating Conditions and V_{CC} =3.0v ~ 3.6v , Tj = -40 $^{\circ}$ C to +85 $^{\circ}$ C)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{ m IL}$	Input Low Voltage	CMOS			$0.3*V_{CC}$	V
$V_{ m IL}$	Schmitt input Low Voltage	CMOS		1.22		V
V_{IH}	Input Hight Voltage	CMOS	$0.7*V_{CC}$			V
V_{IH}	Schmitt input High Voltage	CMOS		2.08		V
V_{OL}	Output low voltage	I _{OL} =2, 4, 8, 12, 16, 24 mA			0.4	V
V_{OH}	Output high voltage	I _{OH} =2, 4, 8, 12, 16, 24 mA	2.3			V
R_{I}	Input Pull-up/down resistance	Vil=0 _V or Vih=V _{CC}		75		ΚΩ

5.6. Crystal Oscillator Circuit Setup for Characterization

The following setup was used to measure the open loop voltage gain for crystal oscillator circuits. The feedback resistor serves to bias the circuit at its quiescent operating point and the AC coupling capacitor, Cs, is much larger than C1 and C2.



5.7. USB Transceiver Characteristics

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARA IETER	C ONDITIONS	LIM MIN	IITS Max	UNIT
V _{CC}	DC supply voltage		3.0	3.6	V
VI	DC input voltage range		0	5.5	V
V _{I/O}	DC input range for I/Os		0	Vcc	V
Vo	DC output voltage range		0	V_{CC}	V
Т _{АМВ}	Operating ambient temperature range in free air	See DC and AC characteristics for individual device	0	70	C

ABSOLUTE MAXIMUM RATINGS (Notes 1 and 2)

In accordance with the Absolute Maximum Rating System, Voltages are referenced to GND (Ground=0v)

SYMBOL	PARA IETER	C ONDITIONS	LIMITS		UNIT
STWIDGE	TAKA ILILIK	CONDITIONS	MIN	MAX	CIVIT
V _{cc}	DC supply voltage		-0.5	+6.5	V
I _{IK}	DC input diode current	Vi<0		-50	mA
Vı	DC input voltage	Note 3	-0.5	+5.5	V
V _{I/O}	DC input voltage range for I/Os		-0.5	Vcc +0.5	V
I _{OK}	DC output diode current	Vo> Vcc or Vo<0		+/-50	mA
Vo	DC output voltage	Note 3	-0.5	Vcc +0.5	V
Io	DC output source sink current for VP/VM and RCV pins	Vo=0 to Vcc		+/-15	mA
Io	DC output source or sink current for D+/D- pins	Vo= 0 to Vcc		+/-50	mA
I_{CC} , I_{GND}	DC Vcc or GND current			+/-100	mA
T _{STO}	Storage temperature range		-60	+150	C
Ртот	Power dissipation per package				mW

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.
 The performance capability of a high performance integrated circuit in conjunction with its thermal
- The performance capability of a high performance integrated circuit in conjunction with its thermal
 environment can create junction temperatures which are detrimental to reliability. The maximum
 junction temperature of this integrated circuit should not exceed 150°C.
- 3. The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (Ground=0V).

				LIMITS	3	
SYMBOL	PARAMETER	TEST (ONDITIONS	-4) ⁰	C to +8	35 ⁰ C	UNIT
			MIN	TYP	MAX	
VHYS	Hysteresis on inputs	Vcc=3.0V to 3.6V (Note 3)	0.3	0.4	0.5	V
VIH	HIGH level input	Vcc=3.0V to 3.6V (Note 3)		1.5	2.0	V
VIL	LOW level input	Vcc=3.0V to 3.6V (Note 3)	0.8	1.1		V
RoH	Output impedance (HIGH state)	Note 2	28	34	43	ohm
RoL	Output impedance (LOW state)	Note 2	28	35	43	ohm
VOH	HIGH level output	Vcc=3.0V Io=6mA	2.2	2.7		V
	(Note 3)	Vcc=3.0V Io=4mA	2.4			
		Vcc=3.0V lo=100µA	2.8			
VOL	LOW level output	Vcc=3.0V Io=6mA		0.3	0.7	V
	(Note 3)	Vcc=3.0V lo=4mA			0.4	
		Vcc=3.0V lo=100µA			0.2	
IQ	Quiescent supply current	Vcc=3.6V VI=Vcc or GND Io=0		330	600	μΑ
Isup	Supply current in suspend	Vcc=3.6V VI=Vcc or GND			70	μΑ
IEC	Active cumply current (Full	lo=0 Vcc=3.3V		9	14	A
IFS	Active supply current (Full Speed)	100 010 1			14	mA
ILS	Active supply current (Low Speed)	Vcc=3.3V		2		mA
ILeak	Imput leakage current	Vcc=3.6V VI=5.5V or		+/-	+/-	μΑ
		GND, not for I/O Pins		0.1	0.5	
IOFF	3-state output OFF-state	Vi=Vih or ViL; Vo=Vcc or			+/-10	μΑ
	current	GND				

NOTES:

- All typical values are at Vcc=3.3V and Tamb=25 C.
 This value includes an external resistor of 24 ohm +/-1%. See "Load D+ and D-" diagram for testing details.
 All signals except D+ and D-.

AC ELECTRICAL CHARACTERISTICS GND=0V, $t_{\scriptscriptstyle R}$ = $t_{\scriptscriptstyle F}$ =3.0 ns; $C_{\scriptscriptstyle L}$ =50 pF; RL=500 Ohms

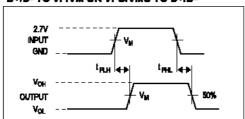
SYMBOL	PAF AMETER	NAVEFORM	MIN	LIN C to +25 TYP	MITS T C MAX	_{АМВ}) 0 ⁰ С to MIN	+70 [°] C MAX	UNIT
tpLH	VMO/VPO to D+/D-	1	0		12	0	14	ns
tpHL	Full Speed		0		12	0	14	
trise	Rise and Fall Times	2	4	9	20	4	20	ns
tfall	Full Speed		4	9	20	4	20	
tRFM	Rise and Fall Time Matching Full Speed		90		110	90	110	%
tpLH	VMO/VPO to D+/D-	1		120	300		300	ns
tpHL	Low Speed			120	300		300	
trise	Rise and Fall Times	2	75		300	75	300	ns
tfall	Low Speed		75		200	75	200	
tRFM	Rise and Fall Time Matching Low Speed		70		130	70	130	%
tpLH tpHL	D+/D- to RCV	3		9	16 16		16 16	ns
tpLH tpHL	D+/D- to VP/VM	1		4 4	8		8 8	ns
tpHZ					12		12	ns
tpZH	OE# to D+/D- RL =	4			12		12	
tpLZ	500ohm				10		10	
tpZL					10		10	
tsu	Setup for SPEED	5	0					ns
Vcr	Crossover point ¹	3	1.3		2.0	1.3	2.0	V

NOTES:

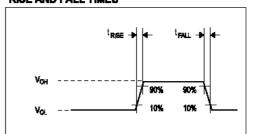
1. The crossover point is in the range of 1.3V to 2.5V for the low speed mode with a 50 pF capacitance.

AC WAVEFORM 1.

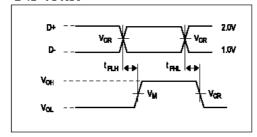
D+/D- TO VP/VM OR VPO/VMO TO D+/D-



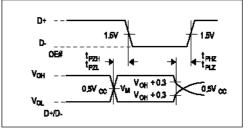
AC WAVEFORM 2. RISE AND FALL TIMES



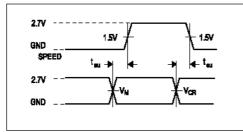
AC WAVEFORM 3. D+/D- TO RCV



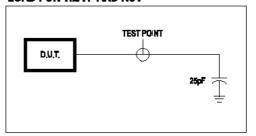
AC WAVEFORM 4. OE# TO D/+/D-



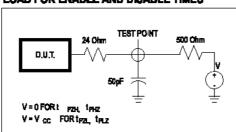
AC WAVEFORM 5. **SETUP FOR SPEED**



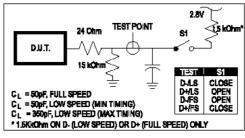
TEST CIRCUIT 1. LOAD FOR VM/VP AND RCV



TEST CIRCUIT 2. LOAD FOR ENABLE AND DISABLE TIMES



TEST CIRCUIT 3. LOAD FOR D+/D-



5.8. ESD Test Results

Test Description: ESD Testing was performed on a Zapmaster system using the Human-Body-Model (HBM) and Machine-Model (MM), according to MIL-STD 883 and EIAJ IC-121 respectively.

- Human-Body-Model stresses devices by sudden application of a high voltage supplied by a 100pF capacitor through 1.5k-ohm resistance.
- Machine-Model stresses devices by sudden application of a high voltage supplied by a 200pF capacitor through very low (0 ohm) resistance.

Test Circuit & Condition

- Zap Interval: 1 second

- Number of Zaps: 3 positive and 3 negative at room temperature

- Criteria: I-V Curve Tracing

ESD Data

Model	lode	S/S	Target	Results
HBM	Vdd, Vss, I/C	15	6000V	PASS
MM	Vdd, Vss, I/C	15	200V	PASS

5.9. Latch-Up Test Results

Test Description: Latch-Up testing was performed at room ambient using an IMCS-4600 system which applies a stepped voltage to one pin per device with all other pins open except Vdd and Vss which were biased to 5Volts and ground respectively.

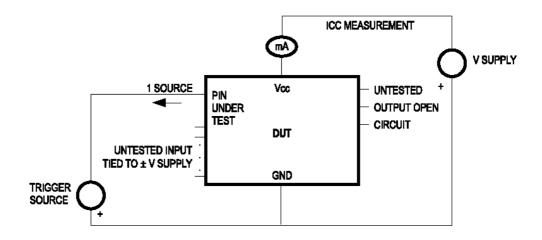
Testing was started at 5.0V (Positive) or 0V (Negative), and the DUT was biased for 0.5 seconds.

If neither the PUT current supply nor the device current supply reached the predefined limit (DUT=00mA, Icc=100mA), then the voltage was increased by 0.1Volts and the pin was tested again.

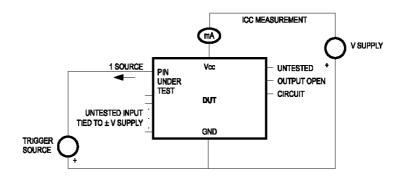
This procedure was recommended by the JEDEC JC-40.2 CMOS Logic standardization committee.

Notes:

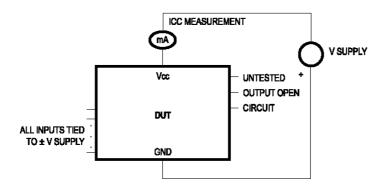
- 1. DUT: The device under test.
- 2. PUT: The pin under test.



Test Circuit: Positive Input/Output Overvoltage/Overcurrent



Test Circuit: Negative Input/Output Overvoltage/Overcurrent



Supply Overvoltage Test

Latch-Up Data

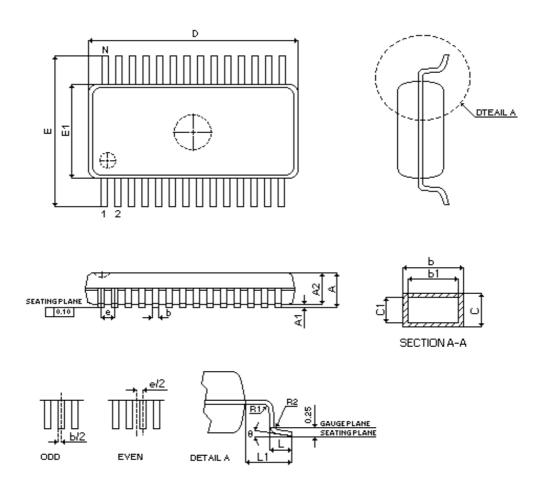
a ep zuu							
Mode		Voltage (V)/CUITENT(ma)	S/S	Results			
X7 . 14	+	11.0	5	Pass			
Voltage	-	11.0	5	Pass			
Current	+	200	5	Pass			
	-	200	5	Pass			
Vdd - Vxx		9.0	5	Pass			

6.0 Mechanical Information

6.1. Normal Size Package (Body Size 209 mil)

Following diagrams show the dimensions of the normal size 28-pin SSOP package.

Measurements are in inches. Dimensions do not include mold flash and dambar protrusion; allowable mold flash is 0.010 inch.

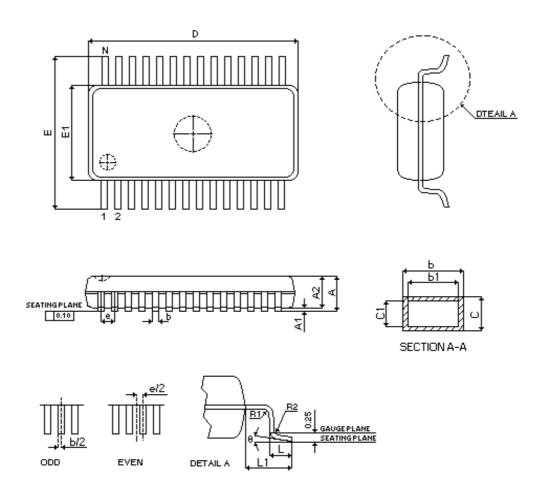


SYMBOL	COMMON DIMENSION MILLIMETERS			COMMON DIMENSION INCH			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A			2.00			0.079	
A1	0.05			0.002			
A2	1.65	1.75	1.85	0.065	0.069	0.073	
b	0.22		0.38	0.009		0.015	
b1	0.22	0.30	0.33	0.009	0.012	0.013	
С	0.09		0.25	0.004		0.010	
c1	0.09	0.15	0.21	0.004	0.006	0.008	
D	9.9	10.2	10.5	0.390	0.402	0.413	
E	7.40	7.80	8.20	0.291	0.307	0.323	
E1	5.00	5.30	5.60	0.197	0.209	0.220	
e	0.65 BSC				0.0256 BSC		
L	0.55	0.75	0.95	0.021	0.030	0.037	
L1	0.25 REF.			0.050 REF.			
R1	0.09			0.004			
θ	0_0	40	80	0_0	40	80	

6.2. Small Size Package (Body Size 150 mil)

Following diagrams show the dimensions of the small size 28-pin SSOP package.

Measurements are in inches. Dimensions do not include mold flash and dambar protrusion; allowable mold flash is 0.010 inch.



SYMBOL	COMMON DIMENSION MILLIMETERS MIN. NOM. MAX.			COMMON DIMENSION INCH MIN. NOM. MAX.			
A	1.35	1.63	1.75	0.053	0.064	0.069	
A1	0.10	0.15	0.25	0.004	0.006	0.010	
A2			1.50			0.059	
b	0.20		0.30	0.008		0.012	
b1	0.20	0.25	0.27	0.008	0.010	0.011	
С	0.18		0.25	0.007		0.010	
D	9.8	9.91	10.01	0.386	0.390	0.394	
E	5.79	5.99	6.20	0.0228	0.236	0.244	
E1	3.81	3.91	3.99	0.150	0.154	0.157	
e	0.635 BSC			0.025 BSC			
L	0.41	0.635	1.27	0.016	0.025	0.050	
L1	0.838 REF.			0.033 REF.			
R1	0.20			0.008			
θ	0_0		80	0_0		8^{0}	

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